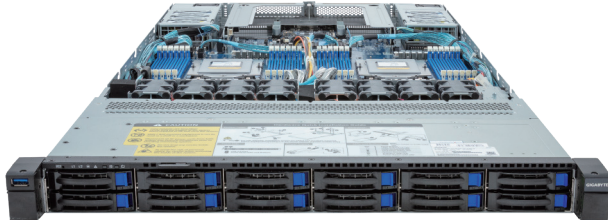


R183-Z92-AAD3

Rack Server - 1U DP 12-Bay SATA/SAS



Key Features

- Dual AMD EPYC™ 9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 12 x 2.5" SATA/SAS hot-swap bays
- 3 x M.2 slots with PCIe Gen3 x4 and x2 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 1600W 80 PLUS Platinum redundant power supply

Application

Networking, Hybrid/Private Cloud Server...

Specification

Dimensions	1U (W438 x H43.5 x D815 mm)
Motherboard	MZ93-FS0
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processors, cTDP up to 300W - OCP NIC 3.0 \leq 21W at 30°C ambient, EPYC 9654 cTDP up to 400W
Sock	2 x LGA 6096 (Socket SP5)
Chipset	System on Chip
Memory	24 x DIMM slots 12-Channel DDR5 RDIMM Up to 4800 MT/s
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2) - Supports NCSI function 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 12 x 2.5" SATA/SAS *SAS card is required to support SAS drives. Internal M.2: 2 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x2
RAID	Require RAID add-in cards
Expansion Slots	2 x FHHL PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots - Supports NCSI function

I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
Backplane Board	Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s
Security Modules	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010
Power Supply	Dual 1600W 80 PLUS Platinum redundant power supply AC Input: 100-240V
System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
System Fans	8 x 40x40x56mm (32,000rpm)
Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Packaging Content	1 x R183-Z92-AAD3, 2 x CPU heatsinks, 1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit Packaging Dimensions: 1045 x 595 x 249 mm
Part Numbers	Barebone package (EPYC 9005/9004): 6NR183Z92DR000ABD3* Barebone package (EPYC 9004): 6NR183Z92DR000AAD3* Optional parts: - 3-Section Rail kit (Supports CMA): 25HB2-A56121-K0R - Cable Management Arm: 25HB1-R18300-K0R - RMA packaging: 6NR183Z92SR-RMA-A100



Learn more at <https://www.GIGABYTE.com/enterprise>

* All specifications are subject to change without notice. Please visit our website for the latest information.
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